NEWS
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SCREEN
DAINIPPON SCREEN MFG. CO., LTD.

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Dainippon Screen Releases New 150WPH Coat / Develop Track for Advanced Deep-UV Lithography.

Dainippon Screen Mfg. Co., Ltd. (Headquartered in Kamigyo-ku, Kyoto; Akira Ishida, President; hereinafter referred to as DNS) announces release of its new 300mm coating/developing system for advanced Deep-UV lithography, RF^3 (pronounced “RF-cubed”). The new track delivers 150 wafers per hour throughput, meeting the demand of next generation scanners. Volume shipments will commence in January 2004 with orders by two top-tier 300mm wafer fab customers already booked for 2003 delivery. Dainippon Screen anticipates significant sale of the new systems and forecasts 30% worldwide track market share by 2005.

In the realm of 90nm IC production and 65 / 45nm development, IC manufacturers are increasingly concerned with the escalating cost of lithography. ArF & KrF scanners and advanced lithography techniques (utilized to extend the limits of optical lithography), demand optimal performance and uptime from the lithography cell. The RF^3 is designed with this concern in mind and delivers the reliability and performance necessary to maximize performance and minimize Cost-of-Ownership (CoO.)

The RF^3 product name embraces the four DNS design concepts critical for today’s market: “Reliable”, “Fast”, “Fine”, and “Flexible. High Reliability is the foundation of the new system, delivering the uptime and consistency mandatory for IC production and integration with state-of-the-art scanners. The RF^3 sets throughput benchmarks with its ultra-Fast 150wph capability. Plans are already in the works to increase this capability to 180wph in the future to meet anticipated scanner productivity increases. Fine CD (critical dimension) control and uniformity is provided by DNS’s core technologies; VPS+ coat, P-RHP post exposure bake, and Slit-Scan develop. This, coupled with advanced PED (post exposure delay) control and integrated metrology options, provides the process performance demanded. The RF^3 is designed with a very Flexible and modular structure providing customer configurable designs with short lead-times and quick installs. Additionally, tool modifications have been significantly simplified.

Dainippon Screen will showcase the RF^3 track at SEMICON West 2003 in San Francisco, on July 14-16. For more information on the RF^3, please contact your local DNS representative or access our e-mail site at www.screen.co.jp.

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The RF^3, 300mm coating/developing system

Please download the photo from
http://www.screen.co.jp/press/nr-photo/indexE.html